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	Document ID	Issue Date	Current OR	Current XRef
1	US 6177350 B1	20010123	438/688	438/622 ; 438/629 ; 438/637 ; 438/643 ; 438/672 ; 438/675
2	US 6156645 A	20001205	438/648	438/656 ; 438/683 ; 438/685
3	US 6139699 A	20001031	204/192.15	204/192.12 ; 204/192.13 ; 204/192.22

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